



# **SPECIFICATION**

(Reference sheet)

- Supplier : Samsung electro-mechanics - Samsung P/N : CL03C010CA3GNNH

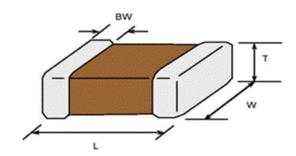
• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1pF, 25V, ± 0.25pF, C0G, 0201

## A. Samsung Part Number

<u>CL</u> <u>03</u> <u>C</u> <u>010</u> <u>C</u> <u>A</u> <u>3</u> <u>G</u> <u>N</u> <u>N</u> <u>H</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor					
2	Size	0201 (inch code)	L: 0.60 ± 0.03 mm	W: $0.30 \pm 0.03 \text{ mm}$			
3	Dielectric	C0G	8 Inner electrode	Cu			
4	Capacitance	<b>1</b> pF	Termination	Cu			
<b>⑤</b>	Capacitance	<b>±</b> 0.25 pF	Plating	Sn 100% (Pb Free)			
	tolerance		9 Product	Normal			
6	Rated Voltage	25 V	10 Special	Reserved for future use			
7	Thickness	0.30 ± 0.03 mm	① Packaging	Cardboard Type, 7" reel			

#### **B. Structure and dimension**



Samsung P/N	Dimension(mm)				
(Lead Free)	L	W	Т	BW	
CL03C010CA3GNNH	0.60 ± 0.03	0.30 ± 0.03	0.30 ± 0.03	0.15 ± 0.05	

#### C. Samsung Reliability Test and Judgement condition

Capacitance Within specified tolerance 1Mb±10% 0.5~5Vrms   Q 420 min			
L. L			
Insulation   10,000Mohm or 500Mohm×μF   Rated Voltage   60~120 sec.			
Resistance Whichever is smaller			
Appearance No abnormal exterior appearance Microscope ('10)	Microscope ('10)		
Withstanding No dielectric breakdown or 300% of the rated voltage	300% of the rated voltage		
Voltage mechanical breakdown			
Temperature C0G			
Characteristics (From -55 °C to 125 °C, Capacitance change should be within ±30PPM/ °C)			
Adhesive Strength No peeling shall be occur on the 500g×F, for 10±1 sec.			
of Termination terminal electrode			
Bending Strength Capacitance change : Bending to the limit (1mm)	Bending to the limit (1mm)		
within ±5% or ±0.5 pF whichever is larger with 1.0mm/sec.	with 1.0mm/sec.		
Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder	SnAg3.0Cu0.5 solder		
is to be soldered newly 245±5℃, 3±0.3sec.	245±5℃, 3±0.3sec.		
(preheating : 80~120 ℃ for 10~30sec.)	(preheating : 80~120 ℃ for 10~30sec.)		
Resistance to Capacitance change : Solder pot : 270±5℃, 10±1sec.	Solder pot : 270±5℃, 10±1sec.		
Soldering heat within ±2.5% or ±0.25pF whichever is larger			
Tan δ, IR : initial spec.			
Vibration Test     Capacitance change :     Amplitude : 1.5mm	Amplitude : 1.5mm		
within ±2.5% or ±0.25pF whichever is larger From 10Hz to 55Hz (return : 1min.)	From 10Hz to 55Hz (return : 1min.)		
Tan δ, IR : initial spec. 2hours ´3 direction (x, y, z)	2hours ' 3 direction (x, y, z)		
Moisture Capacitance change : With rated voltage			
Resistance within ±7.5% or ±0.75pF whichever is larger 40±2°C, 90~95%RH, 500+12/-0hrs	40±2℃, 90~95%RH, 500+12/-0hrs		
Q: 103.33 min			
IR: 500Mohm or 25Mohm × $\mu$ F			
Whichever is smaller			
High Temperature Capacitance change : With 200% of the rated voltage			
Resistance within ±3% or ±0.3pF whichever is larger Max. operating temperature	_		
Q: 210 min 1000+48/-0hrs			
IR : 1,000Mohm or 50Mohm × μF			
Whichever is smaller			
Temperature Capacitance change : 1 cycle condition	1 cycle condition		
Cycling within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger Min. operating temperature $\rightarrow 25^{\circ}$	Min. operating temperature → 25°C		
5 cycle test	5 cycle test		

<sup>\*</sup> The reliability test condition can be replaced by the corresponding accelerated test condition.

### D. Recommended Soldering method:

Reflow ( Reflow Peak Temperature : 260+0/-5℃, 10sec. Max )



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.